

CHINVAY

APPROVAL SHEET

CUSTOMER :

ITME : 6PIN 带锁方型 SIM 卡座

MODEL : SC-1.75- 6C-2.0

MATERIEL NO:

DATE : 08/08/2007

APPROVED BY:

深 圳 市 创 宇 伟 业 科 技 有 限 公 司

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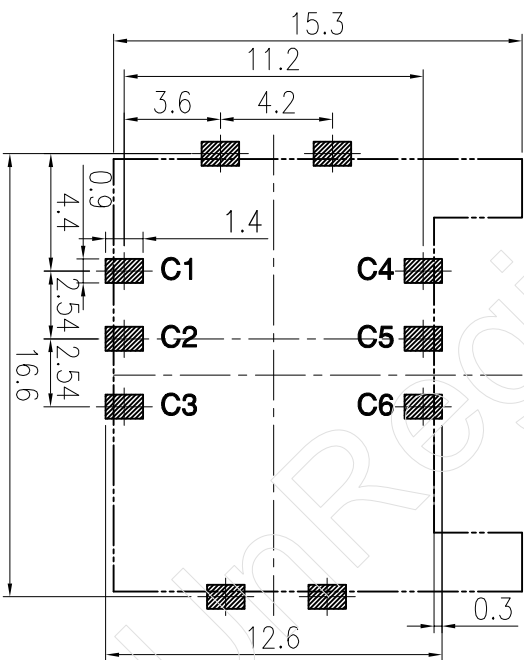
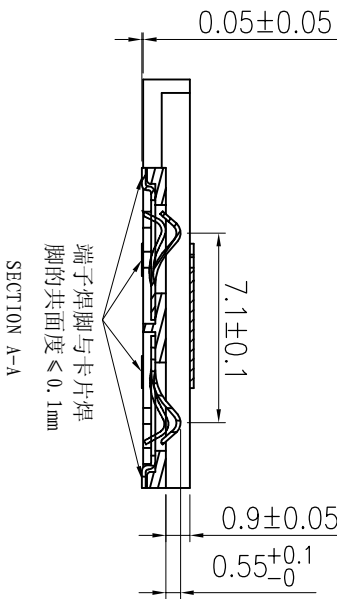
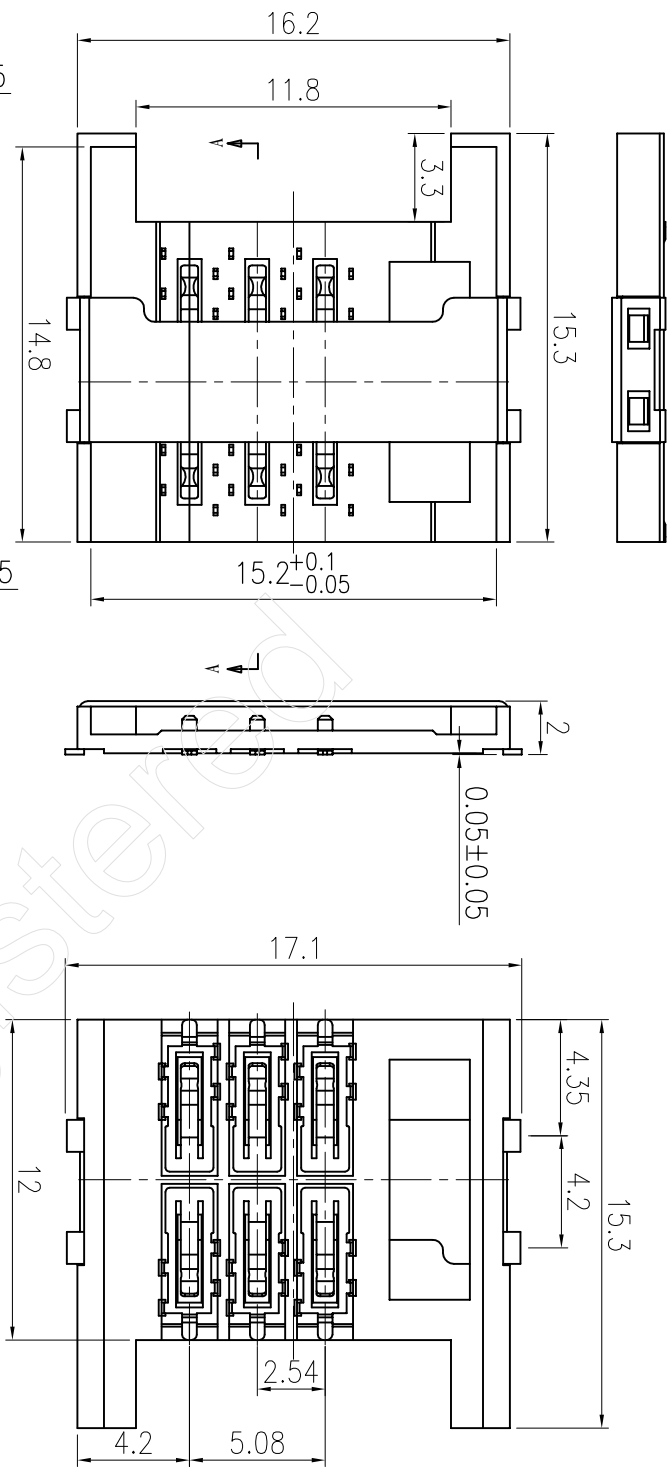
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SC-1.75-6C-2.0

Sim card
Housing height
Position
Height

NOTES:

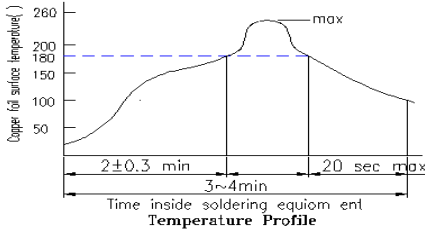
1. MATERIAL SEE TABLE;
2. ACCORD WITH "ROHS";
3. ELECTRICAL PERFORMANCES:
 - 3.1 CURRENT RATING: 1.0A;
 - 3.2 VOLTAGE RATING: 15V Dc;
 - 3.3 INSULATION RESISTANCE: 500MGA OHMS MIN;
 - 3.4 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE;
 - 3.5 CONTACT RESISTANCE: 100 MILLI OHMS MAX;
4. MECHANICAL PERFORMANCES:
 - 4.1 CONTACT NORMAL FORCE FOR 0.5N±0.2N;
 - 4.2 DURABILITY: 5000 CYCLES;
 - 4.3 OPERATING TEMPERATURE: -25° TO +85°.

DIM	TOL	DIM	TOL
x		x	±2°
x	±0.10	x	±1°
xx	±0.05	xx	±1°
xxx	±0.03	xxx	±1°

ITEM	DESCRIPTION	MATERIAL	Q'TY	REMARKS
3	PLATE	COPPER ALLOY, 100μ Sn, 100μ Ni underplated	2	
2	CONTACT	COPPER ALLOY, GOLD PLATING 30g ON CONTACT AREA, GOLD FLASH AT SOLDER AREA, 50 μM NICKEL UNDERPLATING OVERALL	6	
1	HOUSING	L.C.P USAV-0 COLOR BLACK	1	

		深圳市创宇伟业科技有限公司	
REV.	VO.0	APPROVAL:	
FILE NO.	DATE	TITLE:	SIM CARD
DESIGN:		P/N:	SC-1.75-6C-2.0
CHECK:		SHEET:	1/1
		SCALE:	1:1
		UNIT:	mm

系列类型	WINGBLOCK CONNECTOR	编写 WRTN BY:	审核 CHECKED BY	批准 APPROVED BY
型号	SC-1.75-6C-2.0	ZHANG MING	ZHANG BO	WANG WEI
VERSION 版本:	V0.1			
DATE 日期:	2007.10.18	2007.10.16	2007.10.16	2007.10.18
1. SCOPE 适用范围 本规格书适用: “WINGBLOCK CONNECTOR” 系列 This specification covers the requirements for: “WINGBLOCK CONNECTOR”				
2. Rating 额定值: DC 15V 1.0A				
3. CONSTRUCTION 构造				
3.1 Shape and dimensions are subject to drawing. 形状.尺寸根据图面确定.				
3.2 All part not allowed to exist rust 、 crack and poor planting.各部分无生锈、裂痕、电镀不良现象.				
4. Standard test conditions shall be 5 to 35°C in temperature and 45 TO 85% in humidity. 温度 5~35°C , 湿度 45~85% 标准状态下测试。				
Item 项目		Test condition 测试条件		Performance 规格
5. Electronical performance 电气性能				
5.1	Contact resistance 接触阻抗	Being measured at 1 KHz small current contact resistance meter. 在1kHz 小电流下测量。		100mΩ max. 100 毫欧 以下。
5.2	Insulation resistance 绝缘阻抗	Measurements shall be made following application of DC 500 V potential across terminals and across terminals and frame for 1 minute. 在端子之间和端子与壳之间加 DC 500 V 条件下,持续 1 分钟测量。		500MΩ min. 500 兆欧 以上。
5.3	Withstand voltage 耐电压	AC 500 V(50Hz or 60 Hz)shall be applied across terminals and across teminals and frame for one minute. 在端子之间和端子与壳之间加 AC 500 V (50Hz 或 60Hz)条件下,持续 1 分钟测量。		There shall be no breakdown 无击穿现象出现.
6. Mechanical performance 机械性能				
6.1	Operating force 接触压力			0.5N±0.2N/Pin 0.5N±0.2N/Pin
6.2	Range 使用温度范围	在-25~+85°C温度内使用		
7. Durability 耐久性				
7.1	Lift test 寿命试验	5,000 cycles of operation at a rate of 15-18 cycles per minute with unloading 在无负载条件下,以每分钟 15—18 次的速度操作 5,000 次。		(1) Contact resistance 接触阻抗 200mΩ max.200 毫欧 以下 (2) 其它满足机械,电器性能.
7.2	Heat test 耐热试验	85±2°C for 96 hours, test after keeping in normal condition for 60 minutes. 在 85±2°C环境中放 96 小时, 再放在正常环境中, 60 分钟后进行测试。		Insulation resistance 50MΩ min.50 兆欧以上, 其它满足机械,电器性能.
7.3	Humidity test 耐湿试验	40±2°C 90-95%RH for 96 hours, test after keeping in normal condition for 60 min. 在 40±2°C 90—95% RH 环境中放 96 小时, 再放在正常环境中, 60 分钟后进行测试。		Insulation resistance 50MΩ min.50 兆欧以上, 其它满足机械,电器性能.
7.4	Cold test 耐冷试验	At -25±3°C for 96 hours, test after keeping in normal condition for 60 min. 在-25±3°C环境中放 96 小时, 再放在正常环境中, 60 分钟后进行测试。		There shall be no sign of damage mechanicly and electricly 无任何迹象显示机械及电气性能损坏。

<p>7.5</p>	<p>Resistance to soldering heat test 耐焊性试验</p>	<p>soldering iron method: Bit temperature $350 \pm 10^{\circ}\text{C}$ application time 3 ± 0.5 sec application time 3 ± 0.5 sec. However excessive pressure shall not be applied to the terminal. 手焊接的时候温度需控制在 $350 \pm 10^{\circ}\text{C}$, 时间为 3 ± 0.5 秒, 不能在排脚上施加异常压力。</p> <p>Reflow Soldering Conditions: Preheat: Temperature on the copper foil surface should reach 180°C. 2 ± 0.3 minutes after the P.W.B entered into the soldering equipment. Soldering heat: Temperature on the copper foil surface should reach the peak temperature of $260 \pm 5^{\circ}\text{C}$ with in 3 seconds after the P.W.B enter into soldering heat zone.</p> <p>过回流焊条件: 预热: 电镀层表面的温度应达到 180°C, 2 ± 0.3 分钟, 后电路板进入回流焊设备. 回流焊温度: 电镀层表面温度最高为 $260 \pm 5^{\circ}\text{C}$ 且停留不超过 3 秒后电路板进入低温焊接处。</p>  <p style="text-align: center;">Temperature Profile</p>	<p>Without deformation of case or excessive looseness of terminals electrical characteristics shall be satisfied. 本体无变形, 能满足于机械、电气性能。</p>
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